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## (54) SEMICONDUCTOR DEVICE

## (57) Abstract:

**PURPOSE:** To enhance maximum memory capacity and to enhance a mounting density by superposing a semiconductor element and a spacer made of an insulation material in a laminar state in a package.

**CONSTITUTION:** A semiconductor element 1 and a spacer 2 made of an insulation material are superposed in a laminar state in a package. Resin 6 seals the element 1, the spacer 2, the inner terminal of an external lead 4 and fine metal wirings 5. Thus, maximum memory capacity is enhanced, and its mounting density is raised.

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